CLAIMS

[Claim 1]

A probe for a probe card, wherein,

the probe includes a plurality of three-dimensional stress dispersion hollow chambers embedded inside the probe, each chamber having ridges and vertices formed by inner wall surfaces, the plurality of stress dispersion chambers are interconnected by cavities, and at least one of the plurality of stress dispersion chambers communicate with the outside of the probe.

[Claim 2] A probe for a probe card

comprising:

a low-resistance portion made of a metallic layer with low electrical resistance; and

a high-resistance portion, located outside of the low-resistance portion, which has higher electrical resistance than the low-resistance portion and possesses spring properties, wherein

the probe includes a plurality of three-dimensional stress dispersion chambers embedded inside the probe, each chamber having ridges and vertices formed by inner wall surfaces,

the stress dispersion chambers are formed in the high-resistance portion.

[Claim 3]

The probe for a probe card according to Claim 2, wherein

the stress dispersion chambers contain the same metal as the metal forming the low-resistance portion.